

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
- Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.



January 2008

74AC125, 74ACT125 **Quad Buffer with 3-STATE Outputs**

Features

■ I_{CC} reduced by 50%

- Outputs source/sink 24mA
- ACT125 has TTL-compatible outputs

General Description

The AC/ACT125 contains four independent non-inverting buffers with 3-STATE outputs.

Ordering Information

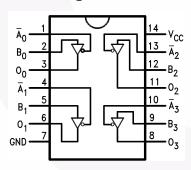
Order Number	Package Number	Package Description			
74AC125SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow			
74AC125SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide			
74AC125MTC	MTC14	4-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide			
74AC125PC	N14A	4-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide			
74ACT125SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow			
74ACT125SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide			
74ACT125MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide			
74ACT125PC	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide			

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.



All packages are lead free per JEDEC: J-STD-020B standard.

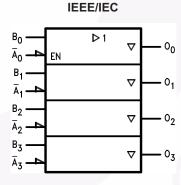
Connection Diagram



Pin Description

Pin Names	Description
\overline{A}_n , B_n	Inputs
O _n	Outputs

Logic Symbol



Function Table

Inp	uts	Output
A _n	B _n	O _n
L	L	L
L	Н	Н
Н	Х	Z

H = HIGH Voltage Level, L = LOW Voltage Level Z = HIGH Impedance, X = Immaterial

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	-0.5V to +7.0V
I _{IK}	DC Input Diode Current	
	$V_{I} = -0.5V$	–20mA
	$V_{I} = V_{CC} + 0.5$	+20mA
V _I	DC Input Voltage	-0.5V to V _{CC} + 0.5V
I _{OK}	DC Output Diode Current	
	$V_{O} = -0.5V$	–20mA
	$V_{O} = V_{CC} + 0.5V$	+20mA
Vo	DC Output Voltage	-0.5V to V _{CC} + 0.5V
Io	DC Output Source or Sink Current	±50mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current per Output Pin	±50mA
T _{STG}	Storage Temperature	−65°C to +150°C
T _J	Junction Temperature	140°C

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating		
V _{CC}	Supply Voltage			
	AC	2.0V to 6.0V		
	ACT	4.5V to 5.5V		
V _I	Input Voltage			
Vo	Output Voltage			
T _A	Operating Temperature —40°C to +8			
ΔV / Δt	Minimum Input Edge Rate, AC Devices: 125m\			
	V _{IN} from 30% to 70% of V _{CC} , V _{CC} @ 3.3V, 4.5V, 5.5V			
ΔV / Δt	Minimum Input Edge Rate, ACT Devices: 125mV/r			
	V_{IN} from 0.8V to 2.0V, V_{CC} @ 4.5V, 5.5V			

DC Electrical Characteristics for AC

		V_{CC} $T_A = +25^{\circ}C$		+25°C	T _A = -40°C to +85°C		
Symbol	Parameter	(V)	Conditions	Тур.	G	uaranteed Limits	Units
V _{IH}	Minimum HIGH Level	3.0	$V_{OUT} = 0.1V$ or	1.5	2.1	2.1	V
	Input Voltage	4.5	V _{CC} – 0.1V	2.25	3.15	3.15	
		5.5		2.75	3.85	3.85	
V _{IL}	Maximum LOW Level	3.0	$V_{OUT} = 0.1V$ or	1.5	0.9	0.9	V
	Input Voltage	4.5	V _{CC} – 0.1V	2.25	1.35	1.35	
		5.5		2.75	1.65	1.65	
V _{OH}	Minimum HIGH Level	3.0	$I_{OUT} = -50\mu A$	2.99	2.9	2.9	V
	Output Voltage	4.5		4.49	4.4	4.4	
		5.5		5.49	5.4	5.4	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -12\text{mA}$		2.56	2.46	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(1)}$		4.86	4.76	
V _{OL}	Maximum LOW Level		$I_{OUT} = 50\mu A$	0.002	0.1	0.1	V
	Output Voltage	4.5		0.001	0.1	0.1	
		5.5		0.001	0.1	0.1	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 12\text{mA}$		0.36	0.44	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(1)}$		0.36	0.44	
I _{IN} ⁽³⁾	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$, GND		±0.1	±1.0	μA
I _{OZ}	Maximum 3-STATE Current	5.5	$\begin{aligned} &V_{I}\left(OE\right)=V_{IL},V_{IH},\\ &V_{I}=V_{CC},V_{GND},\\ &V_{O}=V_{CC},GND \end{aligned}$		±0.25	±2.5	μА
I _{OLD}	Minimum Dynamic	5.5	V _{OLD} = 1.65V Max.			75	mA
I _{OHD}	Output Current ⁽²⁾	5.5	V _{OHD} = 3.85V Min.			– 75	mA
I _{CC} ⁽³⁾	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	μA

Notes:

- 1. All outputs loaded; thresholds on input associated with output under test.
- 2. Maximum test duration 2.0ms, one output loaded at a time.
- 3. I_{IN} and I_{CC} @ 3.0V are guaranteed to be less than or equal to the respective limit @ 5.5V V_{CC} .

DC Electrical Characteristics for ACT

		V _{CC}		T _A = +	+25°C	T _A = -40°C to +85°C	
Symbol	Parameter	(V)	Conditions	Тур.	G	Guaranteed Limits	Units
V _{IH}	Minimum HIGH Level	4.5	$V_{OUT} = 0.1V$ or	1.5	2.0	2.0	V
	Input Voltage	5.5	V _{CC} – 0.1V	1.5	2.0	2.0	
V _{IL}	Maximum LOW Level	4.5	$V_{OUT} = 0.1V$ or	1.5	0.8	0.8	V
	Input Voltage	5.5	V _{CC} – 0.1V	1.5	0.8	0.8	
V _{OH}	Minimum HIGH Level	4.5	$I_{OUT} = -50\mu A$	4.49	4.4	4.4	V
	Output Voltage	5.5		5.49	5.4	5.4	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(4)}$		4.86	4.76	
V _{OL}	Maximum LOW Level	4.5	$I_{OUT} = 50\mu A$	0.001	0.1	0.1	V
	Output Voltage	5.5		0.001	0.1	0.1	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(4)}$		0.36	0.44	
I _{IN}	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$, GND		±0.1	±1.0	μA
I _{OZ}	Maximum 3-STATE Current	5.5	$V_I = V_{IL}, V_{IH};$ $V_O = V_{CC}, GND$		±0.5	±5.0	μA
I _{CCT}	Maximum I _{CC} /Input	5.5	$V_I = V_{CC} - 2.1V^{(6)}$	0.6		1.5	mA
I _{OLD}	Minimum Dynamic	5.5	V _{OLD} = 1.65V Max.			75	mA
I _{OHD}	Output Current ⁽⁵⁾	5.5	V _{OHD} = 3.85V Min.			- 75	mA
I _{CC}	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	μA

Notes:

- 4. All outputs loaded; thresholds on input associated with output under test.
- 5. Maximum test duration 2.0ms, one output loaded at a time.
- 6. May be measured per the JEDEC Alternate Method.

AC Electrical Characteristics for AC

			T _A	_ = +25° L = 50p	C, F	T _A = -40°C C _L =	to +85°C, 50pF	
Symbol	Parameter	$V_{CC}(V)^{(7)}$	Min.	Тур.	Max.	Min.	Max.	Units
t _{PLH}	Propagation Delay,	3.3	1.0	6.5	9.0	1.0	10.0	ns
	Data to Output	5.0	1.0	5.5	7.0	1.0	7.5	
t _{PHL}	Propagation Delay,	3.3	1.0	6.5	9.0	1.0	10.0	ns
	Data to Output	5.0	1.0	5.0	7.0	1.0	7.5	
t _{PZH}	Output Enable Time	3.3	1.0	6.0	10.5	1.0	11.0	ns
		5.0	1.0	5.0	7.0	1.0	8.0	
t _{PZL}	Output Enable Time	3.3	1.0	7.5	10.0	1.0	11.0	ns
		5.0	1.0	5.5	8.0	1.0	8.5	
t _{PHZ}	Output Disable Time	3.3	1.0	7.5	10.0	1.0	10.5	ns
		5.0	1.0	6.5	9.0	1.0	9.5	
t _{PLZ}	Output Disable Time	3.3	1.0	7.5	10.5	1.0	11.5	ns
		5.0	1.0	6.5	9.0	1.0	9.5	

Note:

7. Voltage range 3.3 is 3.3V \pm 0.3V. Voltage range 5.0 is 5.0V \pm 0.5V.

AC Electrical Characteristics for ACT

				λ = +25° L = 50p			to +85°C, 50pF	
Symbol	Parameter	V _{CC} (V) ⁽⁸⁾	Min.	Тур.	Max.	Min.	Max.	Units
t _{PLH}	Propagation Delay, Data to Output	5.0	1.0	6.5	9.0	1.0	10.0	ns
t _{PHL}	Propagation Delay, Data to Output	5.0	1.0	7.0	9.0	1.0	10.0	ns
t _{PZH}	Output Enable Time	5.0	1.0	6.0	8.5	1.0	9.5	ns
t _{PZL}	Output Enable Time	5.0	1.0	7.0	9.5	1.0	10.5	ns
t _{PHZ}	Output Disable Time	5.0	1.0	7.0	9.5	1.0	10.5	ns
t _{PLZ}	Output Disable Time	5.0	1.0	7.5	10.0	1.0	10.5	ns

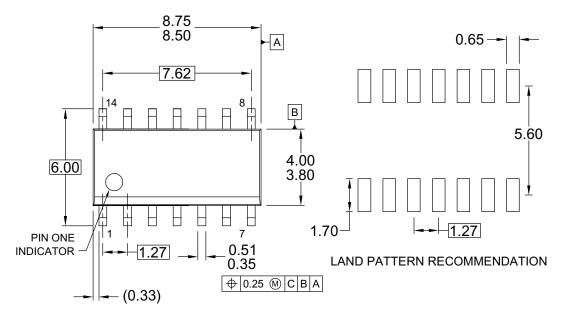
Note:

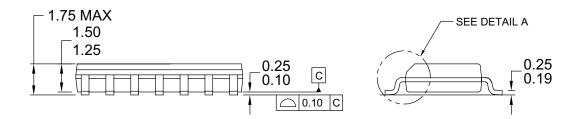
8. Voltage Range 5.0 is $5.0V \pm 0.5V$.

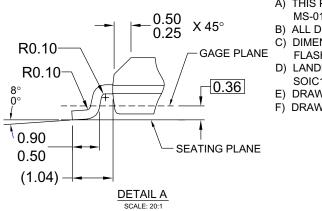
Capacitance

Symbol	Parameter	Conditions	Тур.	Units
C _{IN}	Input Capacitance	V _{CC} = OPEN	4.5	pF
C _{PD}	Power Dissipation Capacitance	$V_{CC} = 5.0V$	45.0	pF

Physical Dimensions







A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,

NOTES: UNLESS OTHERWISE SPECIFIED

- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X145-14M
- E) DRAWING CONFORMS TO ASME Y14.5M-1994
- F) DRAWING FILE NAME: M14AREV13

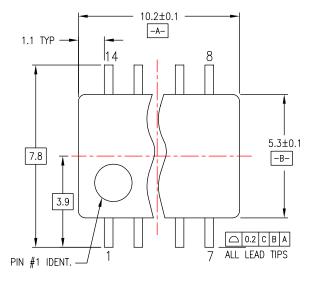
Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

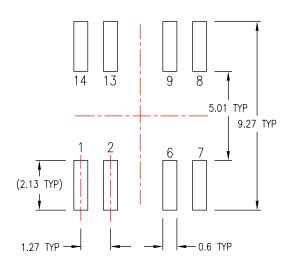
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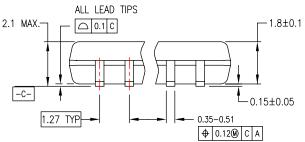
http://www.fairchildsemi.com/packaging/

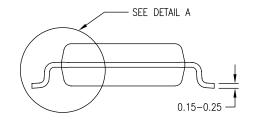
Physical Dimensions (Continued)





LAND PATTERN RECOMMENDATION



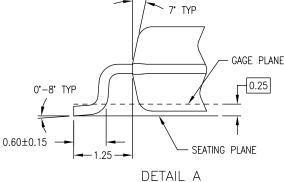


DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD

FLASH, AND TIE BAR EXTRUSIONS.



M14DREVC

Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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Physical Dimensions (Continued) 5.0±0.1 -A-0.65 0.43 TYP 6.4 4.4±0.1 -B-1.65 3.2 □ 0.2 C B A PIN #1 IDENT. 6.10 0.45LAND PATTERN RECOMMENDATION SEE DETAIL A ALL LEAD TIPS 0.90+0.15 1.2 MAX □ 0.1 C 0.09-0.20 -C-0.10±0.05 0.65 0.19 - 0.30⊕ |0.13\\(\) |A |B\(\) |C\(\) 12.00°TOP & BOTTOM R0.09 min GAGE PLANE 0.25 0°-8° NOTES: 0.6±0.1 A. CONFORMS TO JEDEC REGISTRATION MO-153, SEATING PLANE R0.09min VARIATION AB, REF NOTE 6 1 00 **DETAIL A**

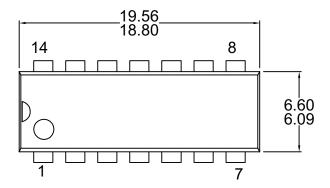
- **B. DIMENSIONS ARE IN MILLIMETERS**
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

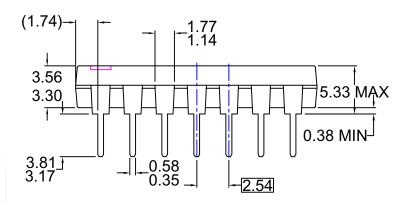
Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

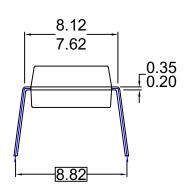
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Physical Dimensions (Continued)







NOTES: UNLESS OTHERWISE SPECIFIED THIS PACKAGE CONFORMS TO

- A) JEDEC MS-001 VARIATION BA
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
 DIMENSIONS ARE EXCLUSIVE OF BURRS.
- C) MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DIMENSIONS AND TOLERANCES PER ASME Y14.5-1994
- E) DRAWING FILE NAME: MKT-N14AREV7

Figure 4. 14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information Formative or In Design		This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.

Rev. 132

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